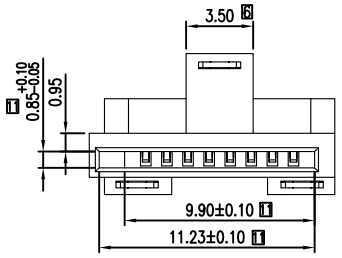
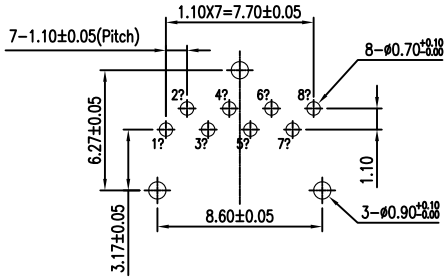
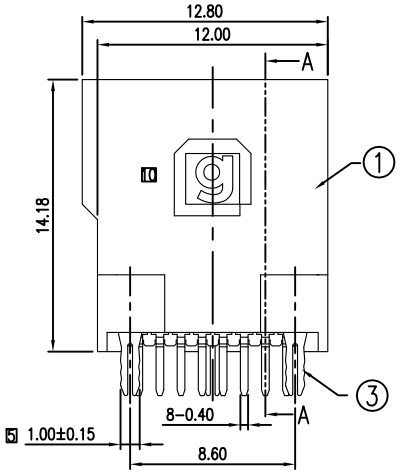
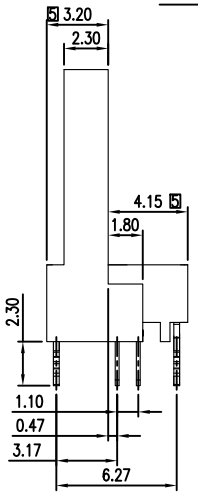
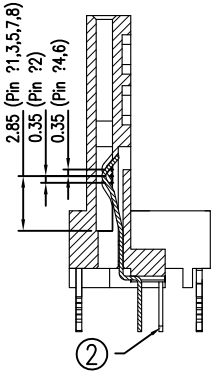




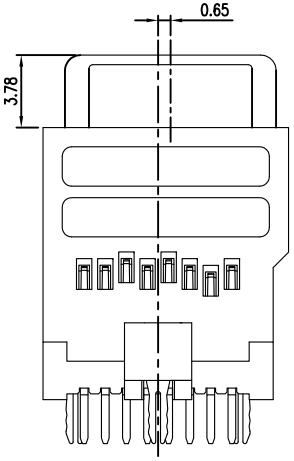
Recomended PCB layout

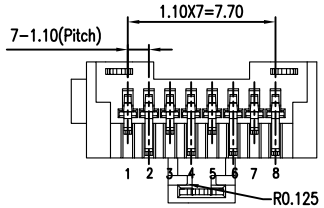






SECTION A-A





Pin?	Description
1	DAT2
2	CD/DAT3
3	CMD
4	V_{DD}
5	CLK
6	V_{SS}
7	DAT0
8	DAT1

REV.	ECN NO.	NAME	DATE
12	CHANGE NOTES 3a, WAS -25°C	AXL	10/3/16'
11	MODIFY TOLERANCE	Terry	07/21/10'
10	ADD LOGO	Terry	07/07/10'
9	ADD FILLET	Terry	05/27/10'
8	ADD CHAMFER	Terry	05/25/10'
7	MODIFY DRAWING	Terry	05/14/10'
6	CONTACT PLATING	Terry	05/04/10'
5	MODIFY BOARD LOCK	Terry	04/29/10'
4	MODIFY BOARD LOCK	Terry	04/27/10'
3	MODIFY DRAWING	Terry	04/22/10'
2	ADD NOTES	Terry	03/26/10'
1	ISSUED	Terry	03/17/10'

TOLERANCE	
LINEAR	ANGLES
X.±0.50	X°.±3°
.X±0.40	.X°±3°
.XX±0.30	.XX°±3°
.XXX±0.15	.XXX°±3°

GENESIS TECHNOLOGY,INC
A Genesis Electro-Mechanical Company
Chung-Yang Rd., Tu-Cheng City, No. 191, Sec. 2 Taipei Hsien, Taiwan

APPD: Allen
CHKD: Daniel
DRWN: Terry
MAT'L:
FINISH:
Q'TY:

TITLE: MICRO SD CARD VERTICAL DIP TYPE
PART NO. MSDV-2008-AKX0T01
DWG NO. GTi10-25051

UNITS	SCALE	SHEET	REV
mm	NONE	1OF2	12

[2] Notes:

1. Electrical:
   a. Voltage Rating: 50VAC (r.m.s)
   b. Current Rating: 0.5Amperes.
   c. Insulation Resistance: 1000M ohms min. initial.
   d. Dielectric Withstand Voltage: AC 500V/1 minute.
   e. Contact Resistance: 100 m ohms max. initial;

2. Mechanical:
   a. Material:
      Contacts: Phosphor Bronze, T=0.2mm.
      [5] Board Lock: Brass, T=0.3mm.
      Housing Flammability Rating: PBT, Black, UL94V-0
   b. Plating: [6]
      Contacts: Gold plated 12u", Solder tail Tin plated 80u", 50u'' nickel underplated overall.
      Board Lock: Tin plated 80u", 50u" nickel underplated overall.
   c. Durability: 10,000 Cycles.
   d. Mating force: 25N Max.
      [7] Unmating force: 1.5N Min.
   e. Solderability: More than 90% of solderable area
   f. Soldering Profile: 260° for 10 seconds without remarkable deterioration.

3. Environmental:
   [12] a. Operating Temperature: -40°C to +85°C.
      Storage Temperature: -40°C to +85°C.
   b. Steady State Humidity: 90%~95% humidity on 40±2°C for 96hours.
   c. Thermal Shock: 5 cycles of -55°C to 85°C.
   d. Vibration Resistance: With dummy card applying DC 100mA,
      Frequency: 10-2000Hz
      Acceleration: 20m/s²
      Sweep rate: 10-2000-10Hz in 5min.
      Duration: 50min.(10 cyc)
      Specimen to be excited along X,Y,and Z axes.(total:150min)
   e. Impact Resistance: With dummy card applying DC 100mA,
      Shock Waveform: Half sinewave
      Acceleration: 490m/s²
      Impact duration: 11msec.
      9 total impacts delivered 3 each along X,Y, and Z axes. (total:9 impacts)
   f. After test, contact resistance increase 40m ohms Max.

4. Compliance:
   a. RoHS Compliance.

[7] PART. NUMBER

MSDV-20 08 - A K X 0 T 01
① ② ③ ④ ⑤ ⑥ ⑦

1. CONNECTOR:
   MSDV: MICRO SD CARD.
2. TYPE
   20: MICRO SD CRAD VERTICAL DIP TYPE
3. POSITIONS
   08: 08 POSITION
4. INSULATOR MATERIAL
   A: PBT
5. INSULATOR COLOR
   K: BLACK
6. CONTACT PLATING
   A: GOLD PLATING 12u'
7. SHIELD PLATING
   0: NONE SHIELD

PART NO.	MSDV-2008-AKX0T01	SHEET	REVISION
DWG NO.	GTi10-25051	2 OF 2	SEE SHEET 1